Qualification Results Summary
WIN 0.5µm pHEMT, MSL 3 Rating Change for LFCSP Package Devices

QUALIFICATION RESULTS			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Temperature Cycle (TC)*	*JEDEC JESD22-A104*	1496	**Pass**
Solder Heat Resistance (SHR)*	*JEDEC/IPC J-STD-020*	897	**Pass**

* These samples were subjected to preconditioning (per j-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C.

Qualification Results Summary
WIN 0.5µm pHEMT, MSL 3 Rating Change for MINI_SO_EP Package Devices

QUALIFICATION RESULTS			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**RESULTS**
Temperature Cycle (TC)*	*JEDEC JESD22-A104*	327	**Pass**
Solder Heat Resistance (SHR)*	*JEDEC/IPC J-STD-020*	63	**Pass**

* These samples were subjected to preconditioning (per j-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: 1. Bake – 24 hours at 125°C; 2. Soak – unbiased soak for 192 hours at 30°C, 60%RH; 3. Reflow – three passes through a reflow oven with a peak temperature of 260°C.